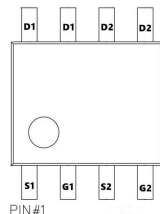
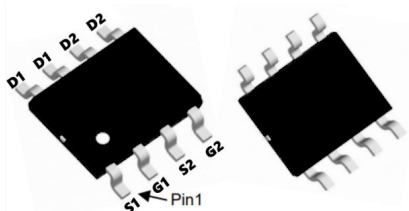
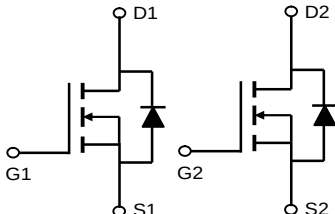


TM08H02S

N+N-Channel Enhancement Mode Mosfet

General Description • Low $R_{DS(ON)}$ • RoHS and Halogen-Free Compliant Applications • Load switch • PWM Product Summary $V_{DS} = 20V$ $I_D = 8.0A$ $R_{DS(ON)} = 20m\Omega (typ.) @ V_{GS} = 4.5V$ 100% UIS Tested 100% R_g Tested 																																																				
S:SOP-8L    Marking: 08V02 OR 9926A																																																				
Absolute Maximum Ratings ($T_A = 25^{\circ}C$ unless otherwise noted) <table><tr><th>Symbol</th><th>Parameter</th><th>Rating</th><th>Units</th></tr><tr><td>V_{DS}</td><td>Drain-Source Voltage</td><td>20</td><td>V</td></tr><tr><td>V_{GS}</td><td>Gate-Source Voltage</td><td>± 12</td><td>V</td></tr><tr><td>$I_D @ T_A = 25^{\circ}C$</td><td>Continuous Drain Current, $V_{GS} @ 4.5V^1$</td><td>8.0</td><td>A</td></tr><tr><td>$I_D @ T_A = 70^{\circ}C$</td><td>Continuous Drain Current, $V_{GS} @ 4.5V^1$</td><td>5.8</td><td>A</td></tr><tr><td>I_{DM}</td><td>Pulsed Drain Current²</td><td>29</td><td>A</td></tr><tr><td>$P_D @ T_A = 25^{\circ}C$</td><td>Total Power Dissipation³</td><td>1.65</td><td>W</td></tr><tr><td>T_{STG}</td><td>Storage Temperature Range</td><td>-55 to 150</td><td>$^{\circ}C$</td></tr><tr><td>T_J</td><td>Operating Junction Temperature Range</td><td>-55 to 150</td><td>$^{\circ}C$</td></tr></table> Thermal Data <table><tr><th>Symbol</th><th>Parameter</th><th>Typ.</th><th>Max.</th><th>Unit</th></tr><tr><td>$R_{\theta JA}$</td><td>Thermal Resistance Junction-ambient ¹</td><td>---</td><td>78</td><td>$^{\circ}C/W$</td></tr><tr><td>$R_{\theta JC}$</td><td>Thermal Resistance Junction-Case¹</td><td>--</td><td>-</td><td>$^{\circ}C/W$</td></tr></table>		Symbol	Parameter	Rating	Units	V_{DS}	Drain-Source Voltage	20	V	V_{GS}	Gate-Source Voltage	± 12	V	$I_D @ T_A = 25^{\circ}C$	Continuous Drain Current, $V_{GS} @ 4.5V^1$	8.0	A	$I_D @ T_A = 70^{\circ}C$	Continuous Drain Current, $V_{GS} @ 4.5V^1$	5.8	A	I_{DM}	Pulsed Drain Current ²	29	A	$P_D @ T_A = 25^{\circ}C$	Total Power Dissipation ³	1.65	W	T_{STG}	Storage Temperature Range	-55 to 150	$^{\circ}C$	T_J	Operating Junction Temperature Range	-55 to 150	$^{\circ}C$	Symbol	Parameter	Typ.	Max.	Unit	$R_{\theta JA}$	Thermal Resistance Junction-ambient ¹	---	78	$^{\circ}C/W$	$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	--	-	$^{\circ}C/W$
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TM08H02S
N+N-Channel Enhancement Mode Mosfet
Electrical Characteristics ($T_J=25^{\circ}\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	20	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =20V, V _{GS} =0V,	-	-	1.0	μA
I _{GSS}	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} =±12V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	0.4	0.7	1.0	V
R _{DS(on)}	Static Drain-Source on-Resistance note2	V _{GS} =4.5V, I _D =6A	-	20	23	mΩ
		V _{GS} =2.5V, I _D =5A -		24	29	
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =10V, V _{GS} =0V, f=1.0MHz	-	358	-	pF
C _{oss}	Output Capacitance		-	69.3	-	pF
C _{rss}	Reverse Transfer Capacitance		-	58.5	-	pF
Q _g	Total Gate Charge	V _{DS} =10V, I _D =3A, V _{GS} =4.5V	-	5.6	-	nC
Q _{gs}	Gate-Source Charge		-	0.8	-	nC
Q _{gd}	Gate-Drain(“Miller”) Charge		-	1	-	nC
Switching Characteristics						
t _{d(on)}	Turn-on Delay Time	V _{DS} =10V, I _D =6A, R _{GEN} =3Ω, V _{GS} =4.5V	-	16	-	ns
t _r	Turn-on Rise Time		-	51	-	ns
t _{d(off)}	Turn-off Delay Time		-	21	-	ns
t _f	Turn-off Fall Time		-	19	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	8	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	24	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} =0V, I _S =6A	-	-	1.2	V

Notes: 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 0.5\%$



Typical Performance Characteristics

Figure 1: Output Characteristics

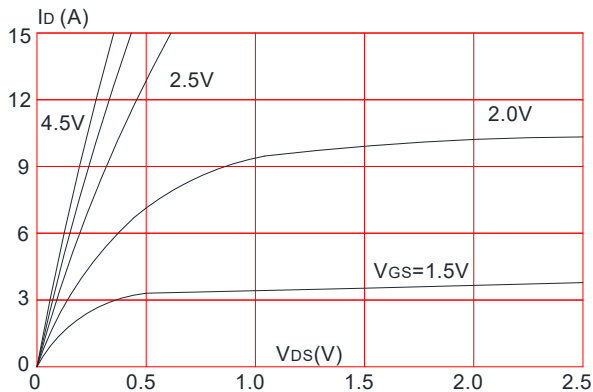


Figure 2: Typical Transfer Characteristics

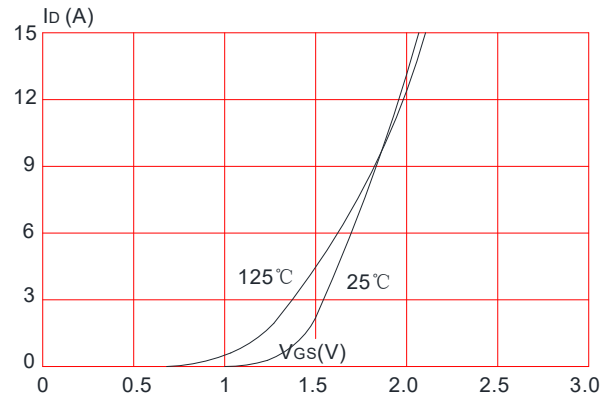


Figure 3: On-resistance vs. Drain Current

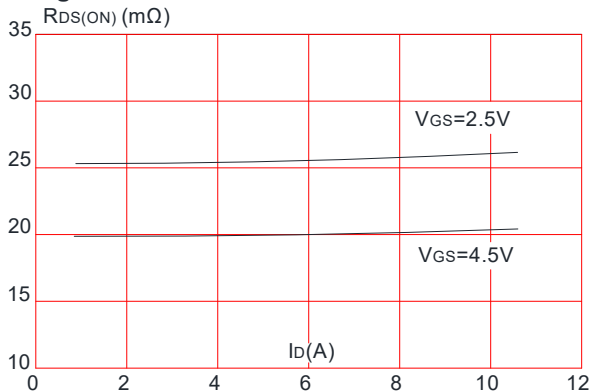


Figure 4: Body Diode Characteristics

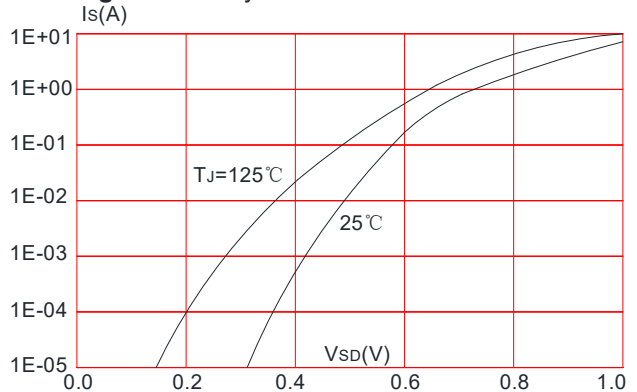


Figure 5: Gate Charge Characteristics

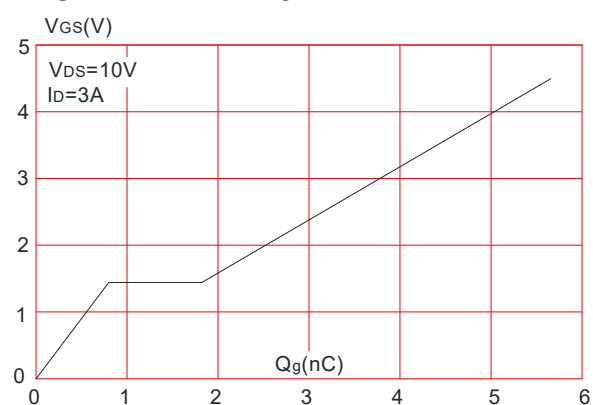
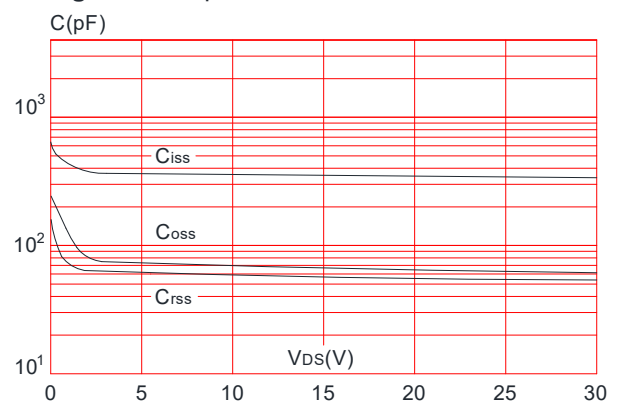


Figure 6: Capacitance Characteristics



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Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

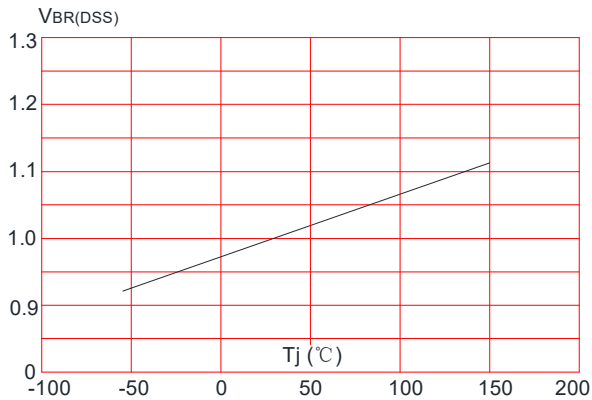


Figure 8: Normalized on Resistance vs. Junction Temperature

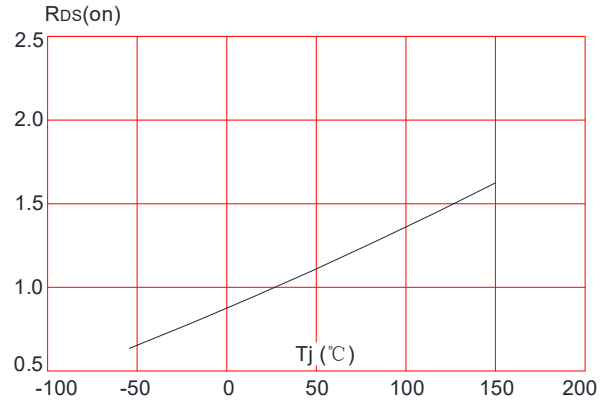


Figure 9: Maximum Safe Operating Area

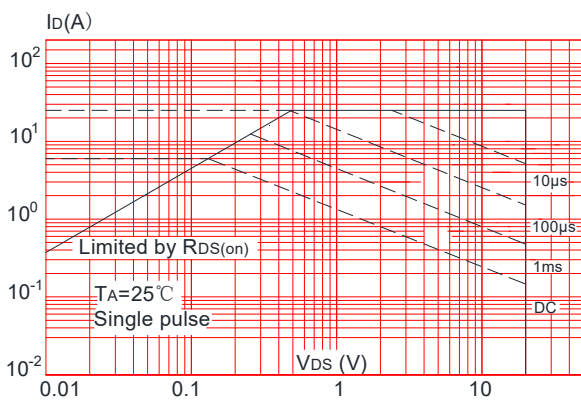


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

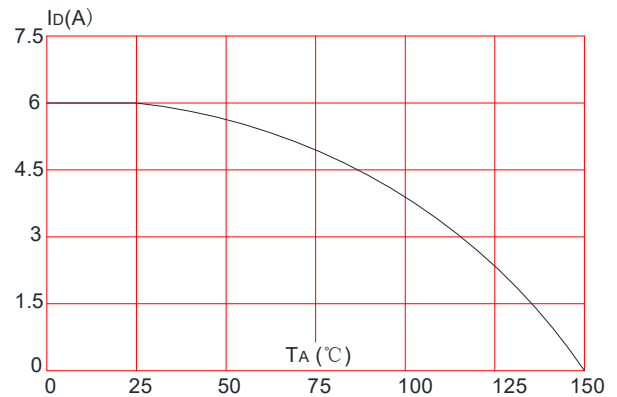
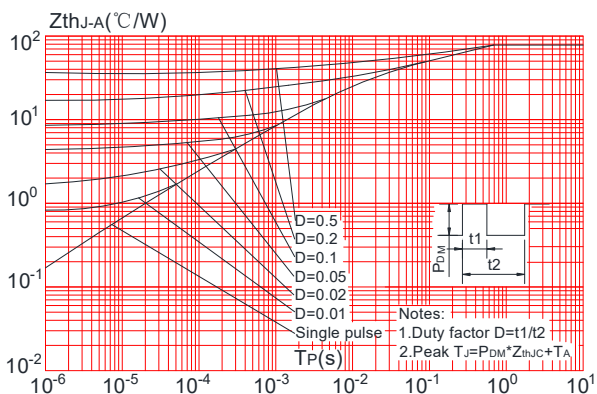
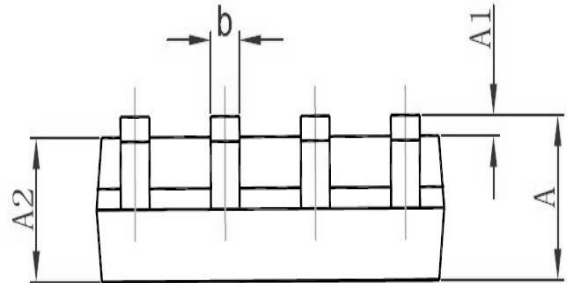
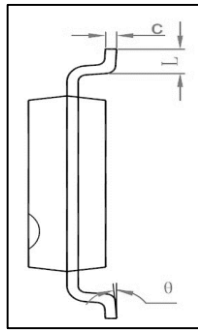
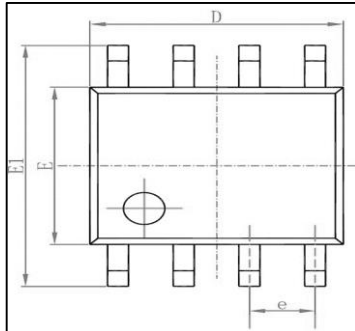


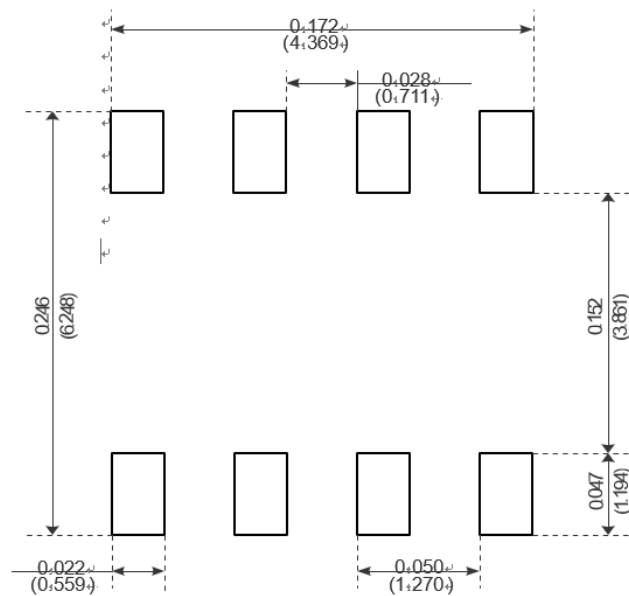
Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



Package Mechanical Data:SOP-8L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270 (BSC)		0.050 (BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°



Recommended Minimum Pads